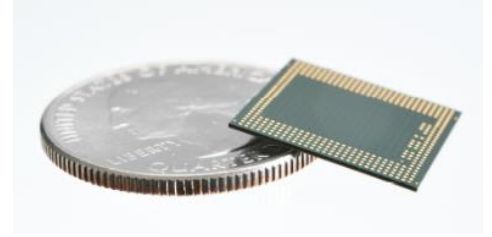


Device Embedded Package ~ MCEP[®] ~

MCEP (Molded Core embedded Package) is a patented and registered trademark of SHINKO ELECTRIC INDUSTRIES CO., LTD

Introduction

MCEP[®] is a semiconductor package that contains IC chips and active/passive components. MCEP[®] is a compact and thin packaging solution developed by SHINKO's unique semiconductor packaging technology. This package, having superior electrical characteristics and high reliability, is used in small-sized electronic devices and various modules.

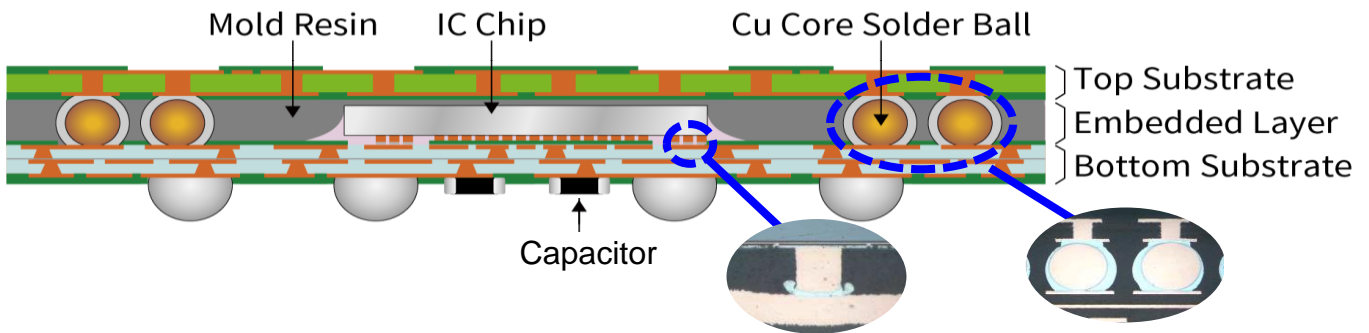


Features

- Assembled IC chips and active/passive components using conventional assembly processes
- Robust semiconductor package structure achieving low warpage while combining small size and low-profile ideal for POP applications
- High design flexibility on the package surface
- High assembly yield and high reliability backed by a long history of mass production

Structure

■ Standard MCEP[®]



■ Option : Enhanced thermal performance modules (under development)

